

MPT

MANUAL PULL TESTER

A compact and intuitive pull tester designed for accurate destructive and non-destructive bond strength testing of fine wire interconnections.



PULL TESTER

FINE Z-ADJUSTMENT

DIAL GAUGE

15–100 μm WIRE
RANGE

Flexible by design

The MPT Manual Pull Tester is a compact and cost-effective solution for bond strength verification in R&D, quality control and production environments. Designed for both destructive and non-destructive pull testing, the MPT delivers reliable test results with simple operation and excellent repeatability.

Explore the possibilities

KEY BENEFITS

- Compact desktop design
- Destructive and non-destructive testing
- Easy dial gauge reading
- Fast test setup and operation
- Suitable for fine wire applications
- Optional microscope and camera configurations

Contact Micronnect for configuration advice, a demonstration, training and service.

Technology and configuration

Compact, precise and easy to operate, the MPT delivers reliable bond strength testing for laboratory and production environments.

01 Accurate Pull Testing

Designed for reliable bond strength evaluation of wire bonded devices.

02 Adjustable Test Setup

Fine vertical positioning and adjustable hook alignment ensure consistent measurements.

03 Multiple Test Ranges

Available with various pull force ranges to support different wire diameters and applications.

04 Flexible Inspection Options

Available with binocular or trinocular microscope systems for improved sample observation.

TECHNICAL DATA

Pull Force Ranges	1.5- 15 g / 3-30 g / 5-50 g / 10-100 g / 25-250 g
Vertical Travel	10 - 150 mm
Work Platform	200 x 200 mm
Work Height	100 mm
Hook diameter	Up to 200 µm
Capillary / tool	Ø 1,58 mm
Dimensions	250 x 200 x 250 mm
Weight	2 kg

Specifications are based on the supplied product information. Final execution may vary by configuration.

OPTIONS

-  Fine Motion X-Y-Theta Stage
-  Binocular Microscope
-  Trinocular Microscope with Camera
-  Additional light source

The adjustable preset test value allows bond integrity verification without damaging the device under test, making it ideal for process validation and quality control.

Find the right configuration for your process

Contact us for technical advice or a demonstration.

CONTACT